

FEATURES

| Surface Mounting Design 8.3*8.3*6.0mm | High Current Handling Capability 20000A @ 8/20 µs | Low Capacitance and Insertion Loss

Quick Response and Long Service Life

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| Moisture sensitivity level: Level 1



8.3*8.3*6.0mm



APPLICATION INFORMATION

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Repeaters, Modems

| Telephone Interface,Line cards.

Data communication equipment.

AGENCY APPROVALS

| lcon | Solderability | |
|---------------------|------------------------------------|--|
| RoHS | Compliance with 2011/65/EU | |
| HF | Compliance with IEC61249-2-21:2003 | |
| ® | Mean lead free | |
| <i>1</i> R ° | UL Certificated E505857 | |

PRODUCT CHARACTERISTICS

| Lead Material | Body Material | Terminal Finish |
|-----------------------|---------------|-----------------------|
| Copper or Fe-Ni alloy | Ceramics | 100% Matte-Tin Plated |



ELECTRICAL PARAMETER

| Parameter | Condition | Rating | Unit |
|-----------------------------------|-----------------------|-------------------------------------|------|
| DC Spark-over Voltage 1) | 100V/s | 376-564 | |
| Impulse Spark-over Voltage | At 1kV/μs | for 99 % of measured values ≤1000 | V |
| impuise spair-over voltage | At 1kV/μs | Typical values of distribution ≤950 | |
| Discharge Current (8/20us) 2) | 10 times | 20 | KA |
| AC Discharge Current | 50Hz, 1S | 20 | А |
| Minimum Insulation Resistance | Test Voltage DC=250V | 1 | GΩ |
| Max. Capacitance 1MHz | V _{DC} =0.5V | 1.5 | рF |
| Operating and Storage Temperature | | -40~125 | °C |

¹⁾ In ionized mode

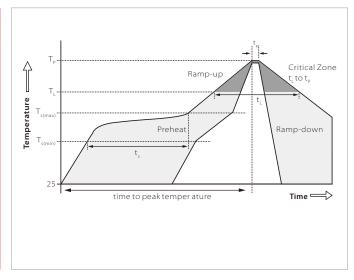
ENVIRONMENTAL RELIABILITY CHARACTERISTICS

| Testing items | Technical standards | |
|-------------------------------|---|--|
| High Temperature Storage Test | Temperature: 85°C ;Time:2H | |
| Low Temperature Storage Test | Temperature: -40°C; Time:2H | |
| Vibration | Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min | |
| Resistance of soldering heat | Temperature: 260±5°C; Time of dip soldering: 10s, 1time | |

NOTE: Up-screen program can be specified by customer's request via contacting Semiware service

REFLOW PROFILE

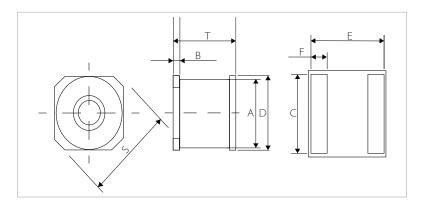
| Reflow Condition | | Lead-free assembly | |
|--|--|--------------------|--|
| | Temperature Min | 150°C | |
| Pre Heat | Temperature Max | 200°C | |
| | Time(min to max) | 60-180 secs | |
| Average ramp up rate (Liquidus)Temp (T_L) to peak T_s (max)to T_L - Ramp-up Rate | | 3°C/second max | |
| Doflow | Temperature (T _L) (Liquidus) | 217℃ | |
| Reflow | Temperature (T_L) | 60-150 seconds | |
| PeakTem | perature (T,) | 260+0/-5°C | |
| Time within 5°C of actual peak Temperature (tp) | | ~10 seconds | |
| Ramp-down Rate | | 6°C/second max | |
| Time 25°C to peak Temperature (T₂) | | 8 minutes max. | |
| Do not ex | kceed | 260°C | |



²⁾ Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

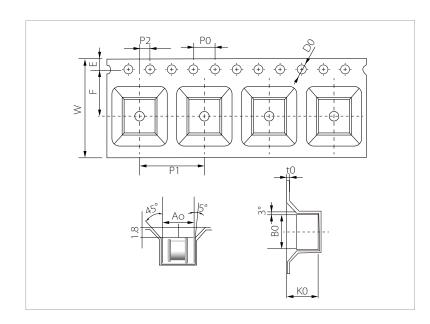


DIMENSIONS AND RECOMMENDED SOLDERING PAD



| Ref. | mm |
|------|----------|
| А | 8.0±0.2 |
| В | 0.5±0.1 |
| С | 9.0 |
| D | 8.3±0.2 |
| Е | 6.7 |
| F | 1.2 |
| Т | 6.0±0.25 |
| S | 9.0±0.4 |

PACKAGE REEL INFORMATION



| Ref. | mm |
|------|-----------|
| W | 16.0±0.3 |
| PO | 4.0±0.1 |
| P1 | 12.0±0.1 |
| P2 | 2.0±0.1 |
| D0 | 1.55±0.05 |
| E | 1.75±0.1 |
| F | 7.5±0.1 |
| A0 | 6.35±0.1 |
| K0 | 6.55±0.1 |
| ВО | 8.65±0.1 |
| tO | 0.5±0.1 |

ORDERING INFORMATION

| Part Number | Size | Marking | QTY/Reel | Reel Size |
|-------------|---------------|--------------------------|----------|-----------|
| SG2R08B470A | 8.3*8.3*6.0mm | % SG470 <u>08</u> | 600 | 13″ |



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